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(12) **United States Design Patent** (10) **Patent No.:** **US D922,609 S**
Tokimatu et al. (45) **Date of Patent:** **** Jun. 15, 2021**

(54) **HOLDING PAD FOR SUBSTRATE TRANSFER**

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(**) Term: **15 Years**

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(30) **Foreign Application Priority Data**

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(51) **LOC (13) Cl.** **24-02**

(52) **U.S. Cl.**
USPC **D24/225**

(58) **Field of Classification Search**
USPC D24/110, 110.5, 169, 211, 223, 224, 225,
D24/230; D10/74, 108; D8/352, 397;
D23/225, 231, 232
CPC A61B 18/148; A61B 18/1482; A61B
18/1487; F04B 1/00; F04B 1/10; F04B
1/12
See application file for complete search history.

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(57) **CLAIM**

The ornamental design for a holding pad for substrate transfer, as shown and described.

DESCRIPTION

FIG. 1 is an isometric view of a holding pad for substrate transfer showing our new design.

FIG. 2 is a reversed isometric view thereof.

FIG. 3 is a top plan view thereof.

FIG. 4 is a bottom plan view thereof.

FIG. 5 is a side elevational view thereof.

FIG. 6 is a cross sectional view thereof taken along cut lines 6-6 of FIG. 3.

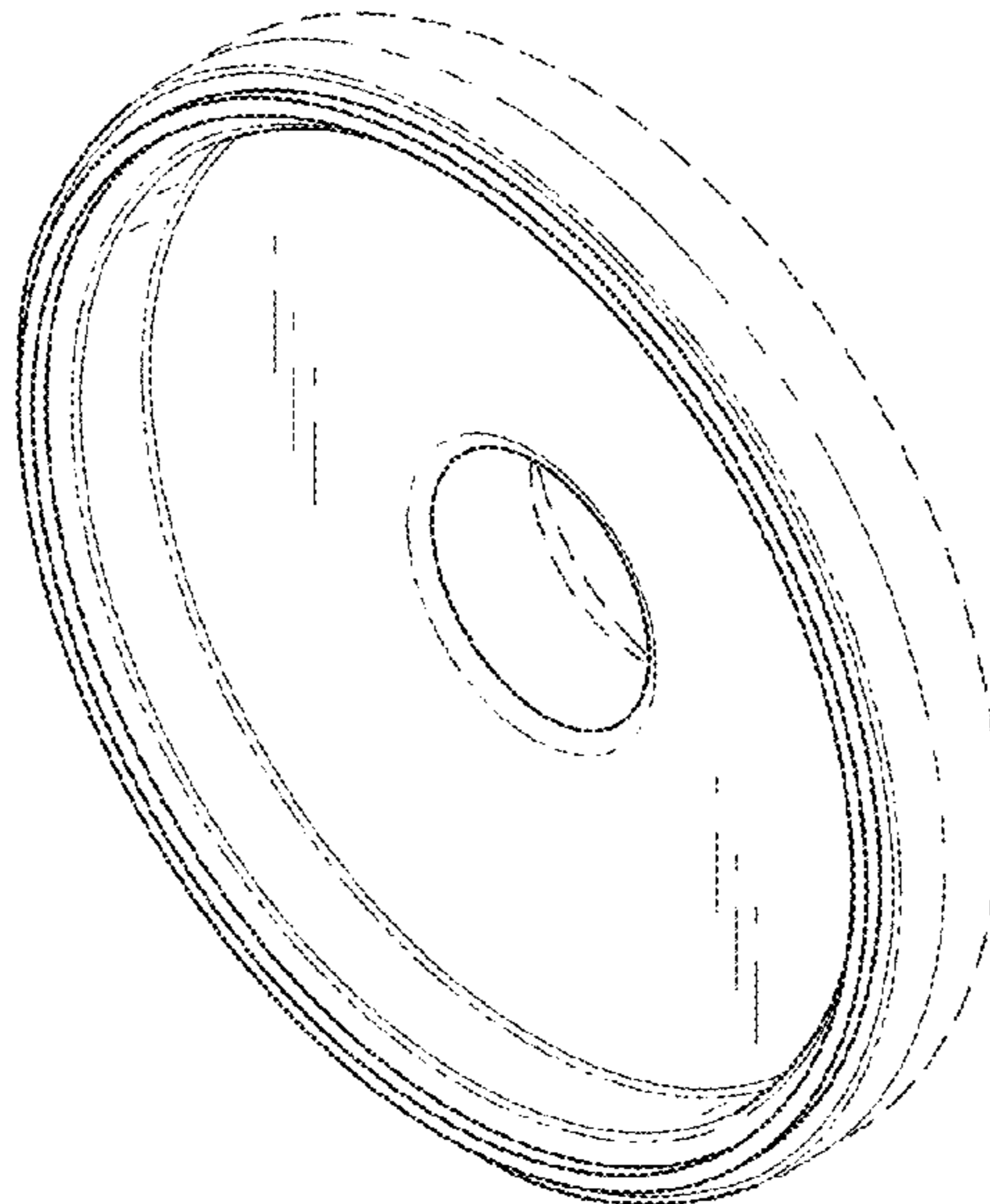
FIG. 7 is another side elevational view thereof.

FIG. 8 is another side elevational view thereof; and,

FIG. 9 is another side elevational view thereof.

The dashed lines in the drawings depict portions of the holding pad for substrate transfer that form no part of the claimed design. The dash-dot-dot lines in the drawings represent contours and shading and form no part of the claimed design. The short dash-short dash-long dash lines depict the boundaries of the claim and form no part thereof.

1 Claim, 9 Drawing Sheets



(56)

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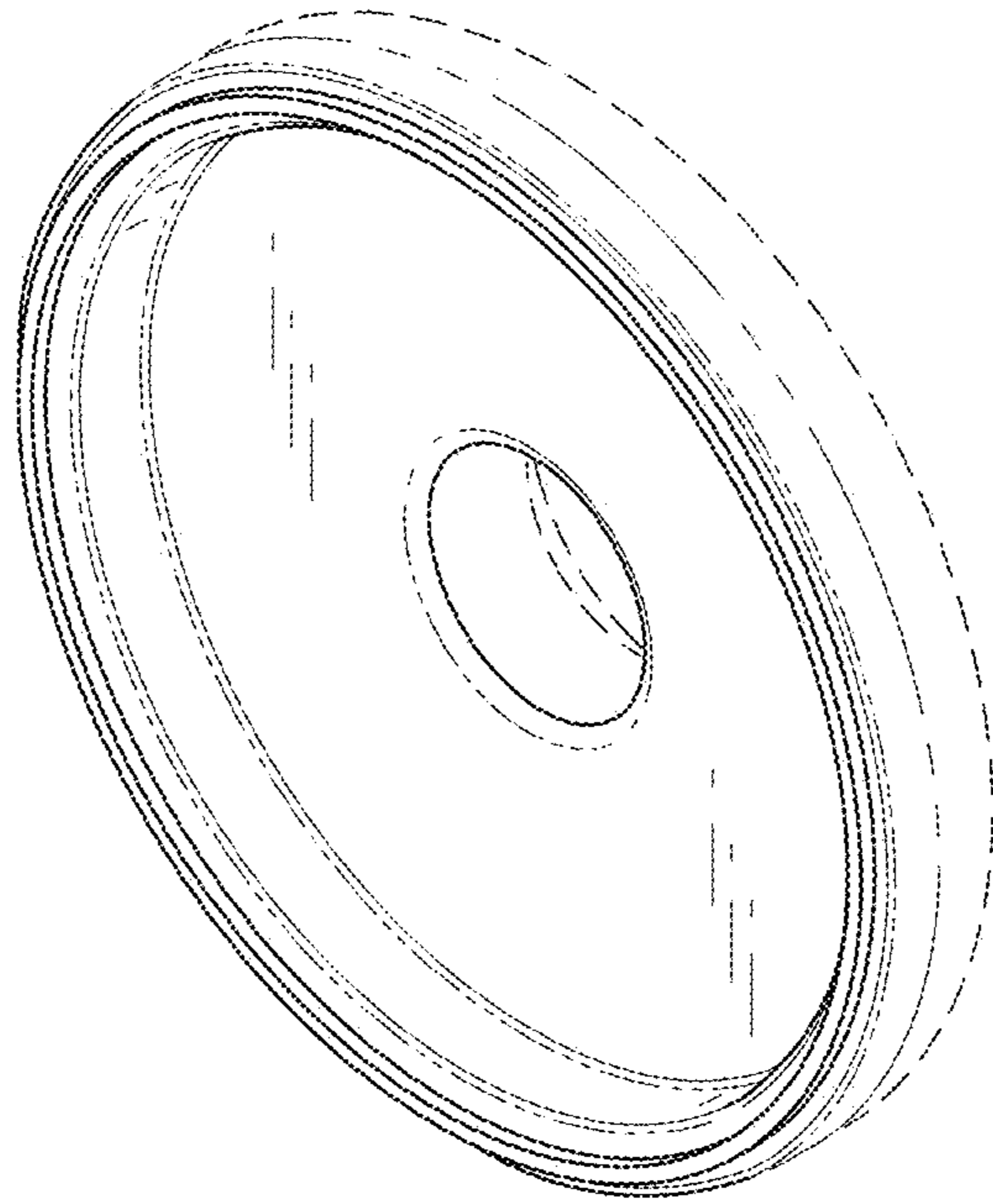


FIG. 1

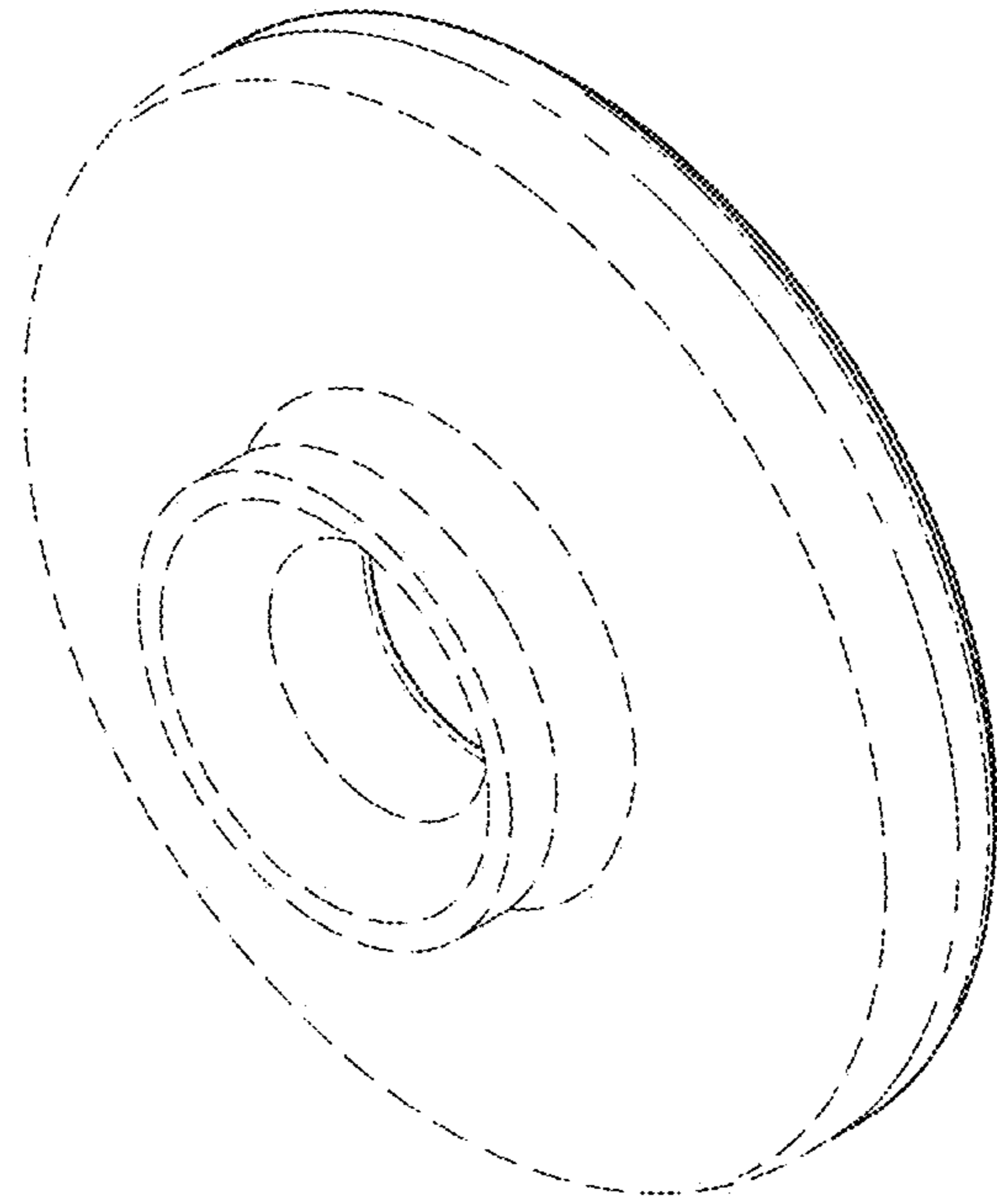


FIG. 2

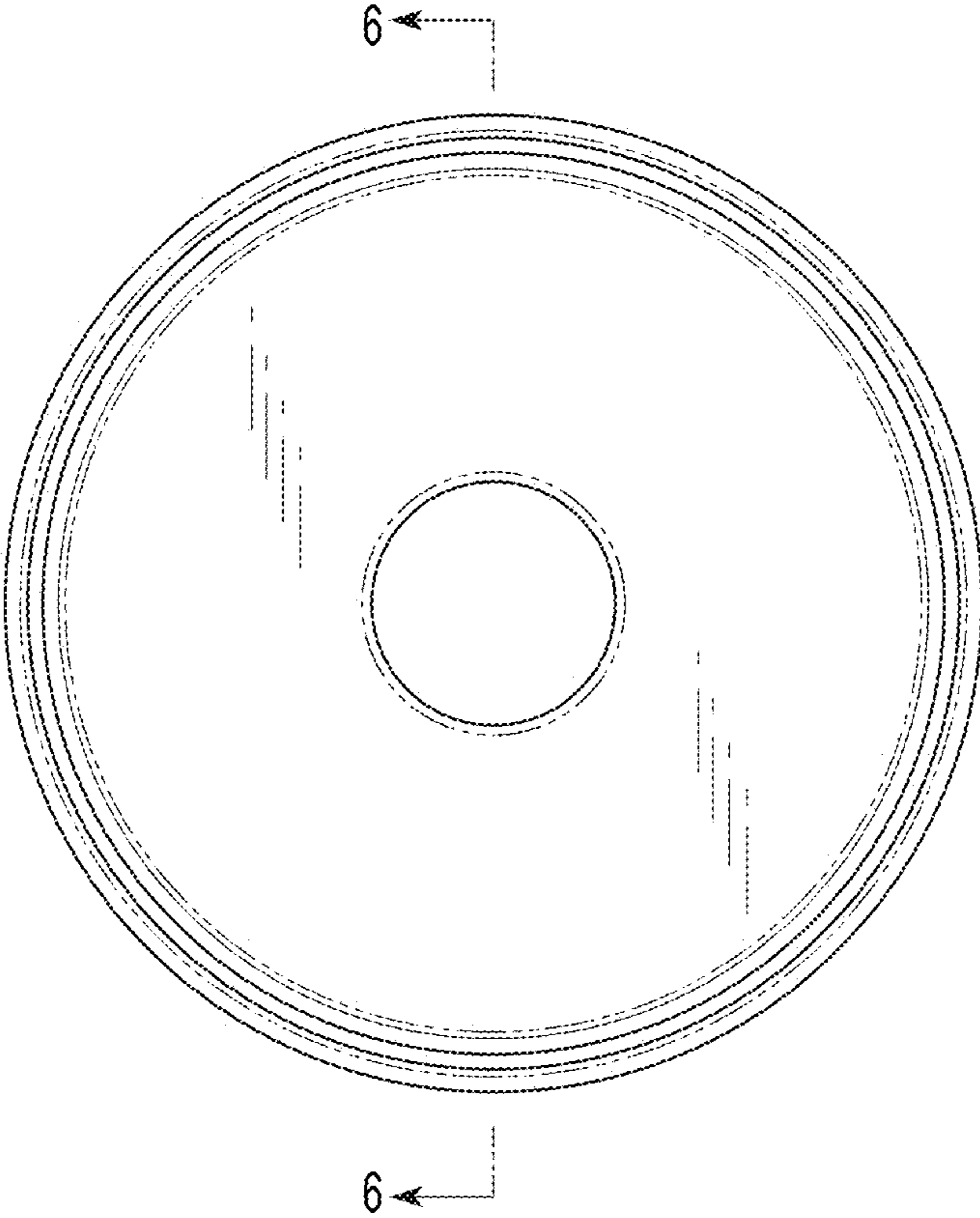


FIG. 3

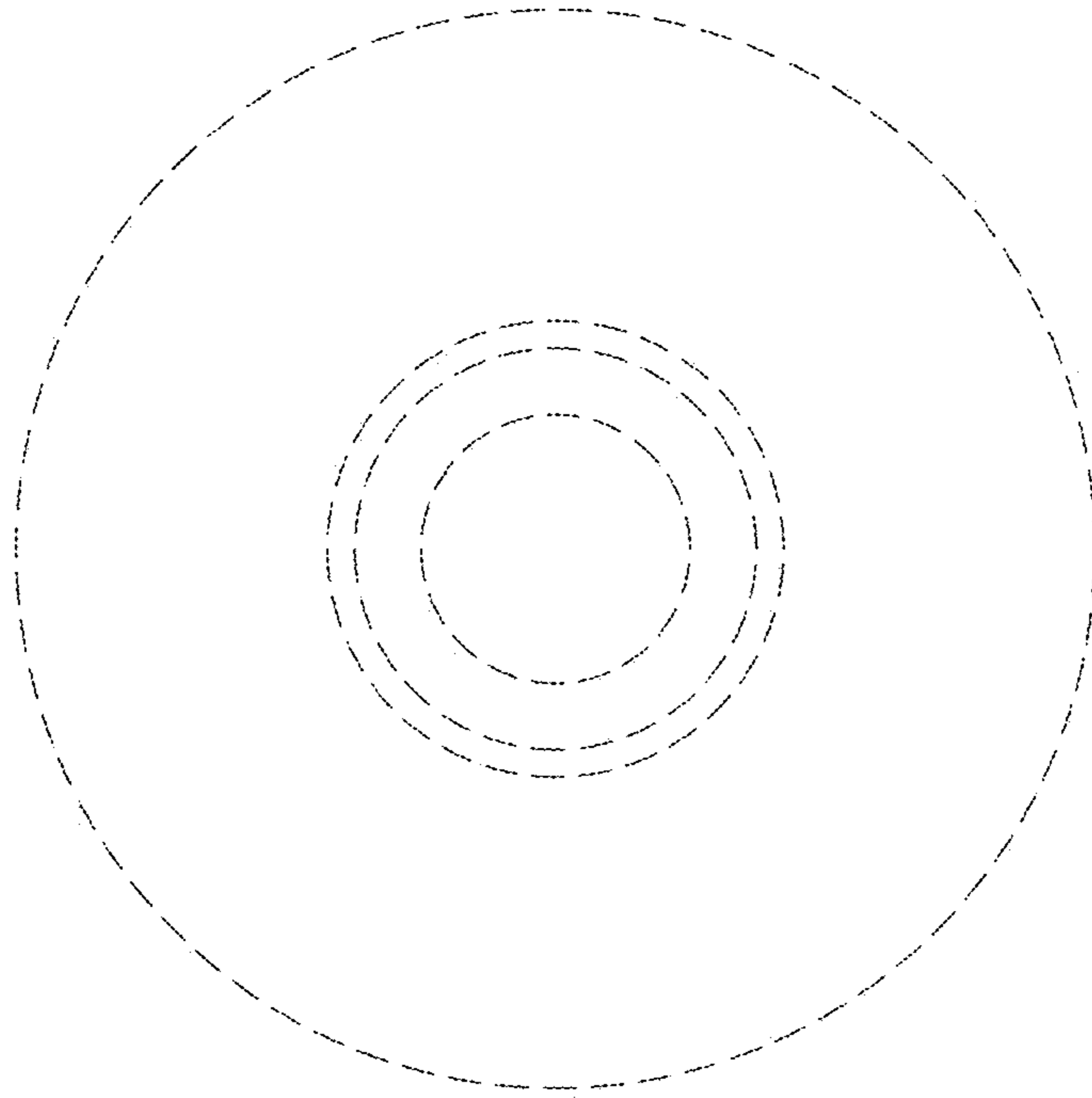


FIG. 4

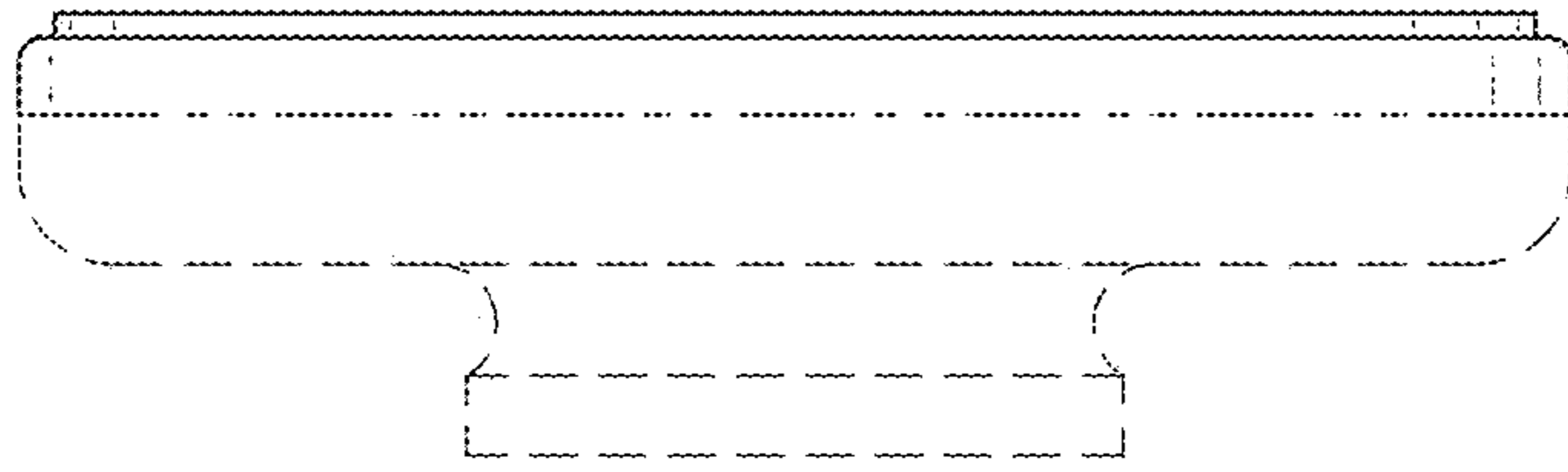


FIG. 5

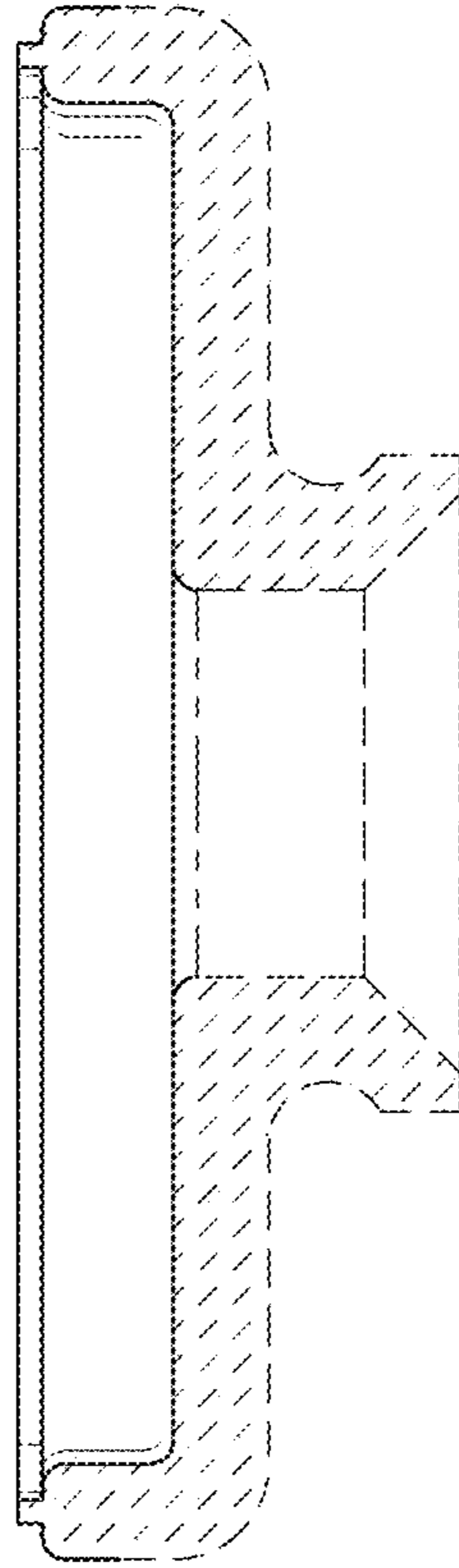


FIG. 6

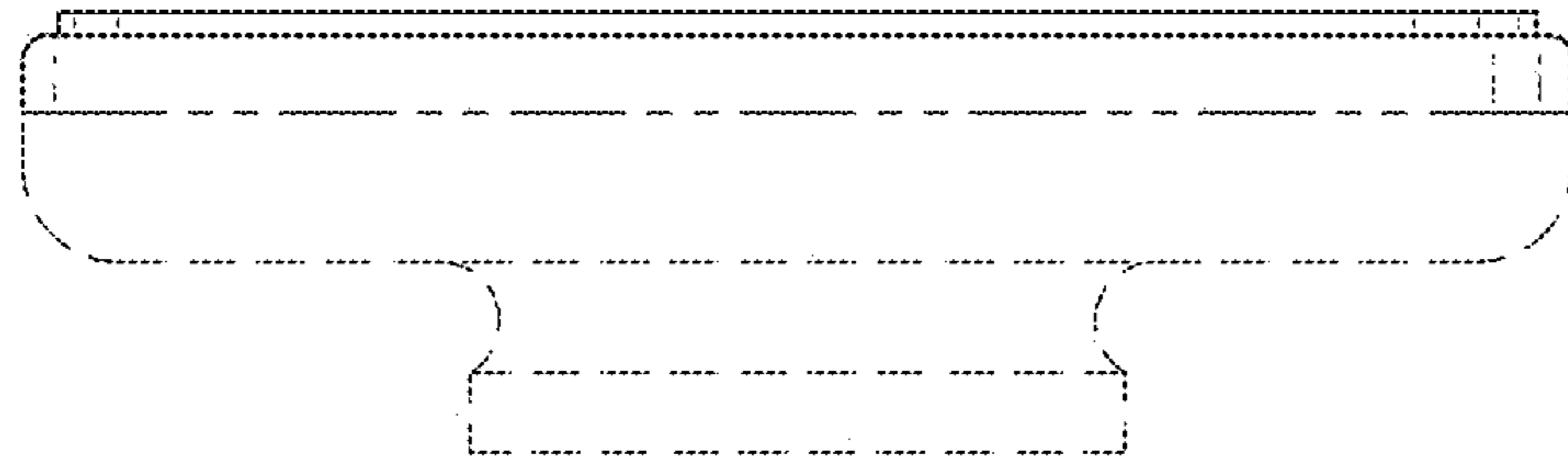


FIG. 7

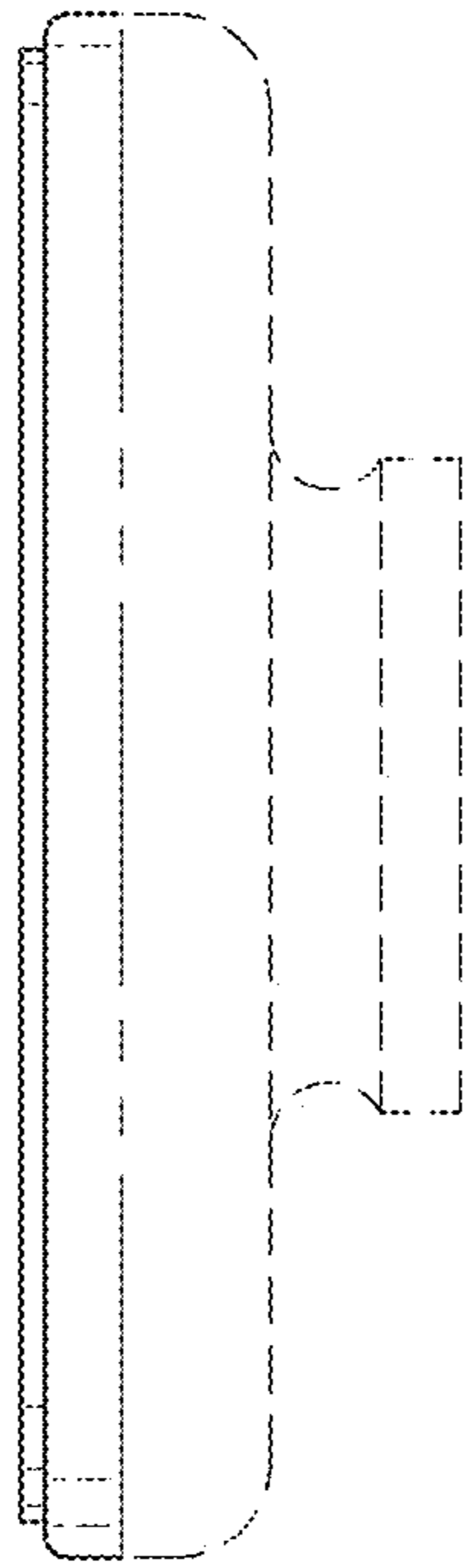


FIG. 8

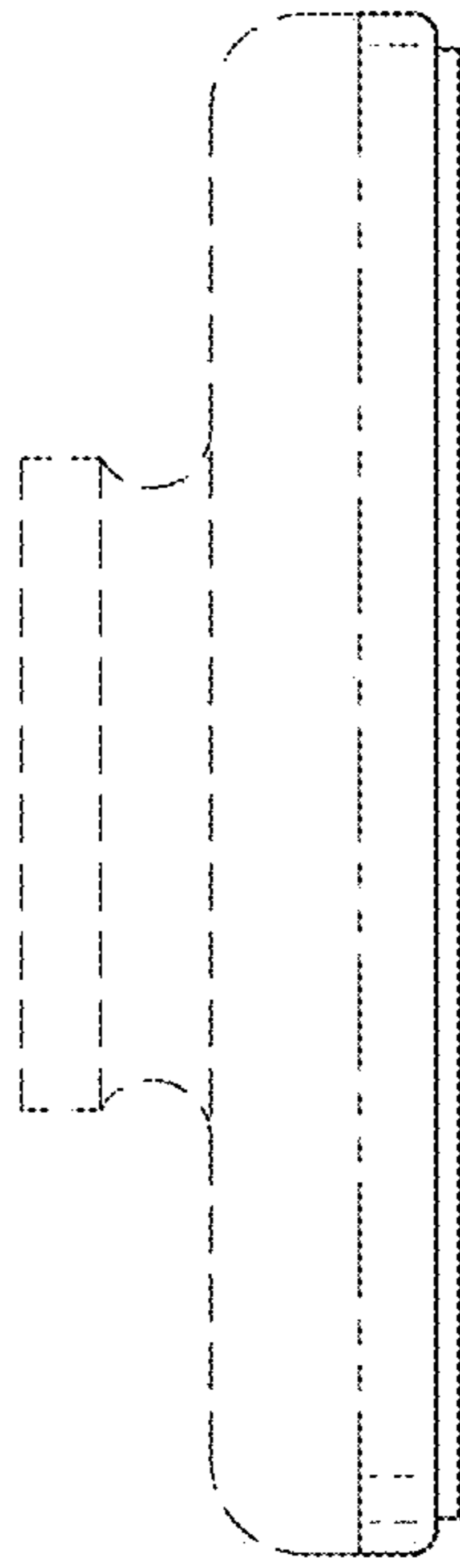


FIG. 9